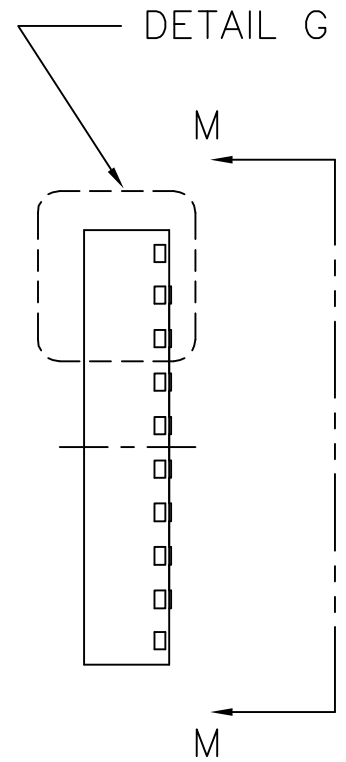
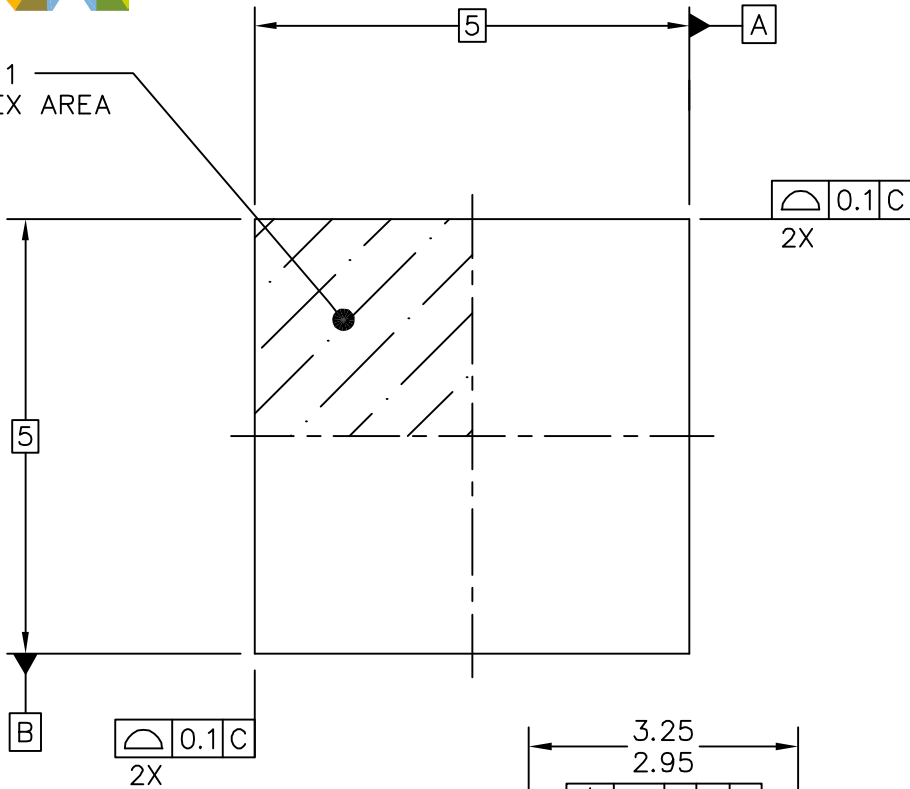
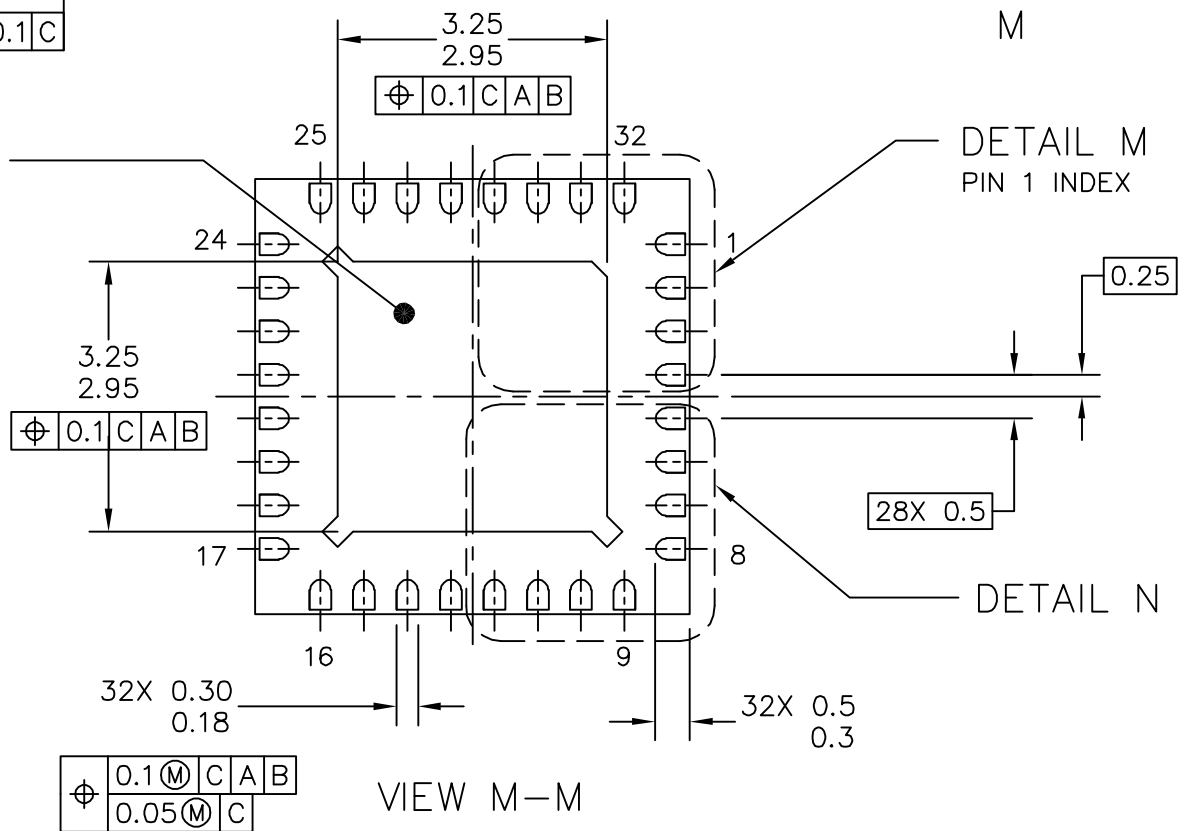




PIN 1 INDEX AREA

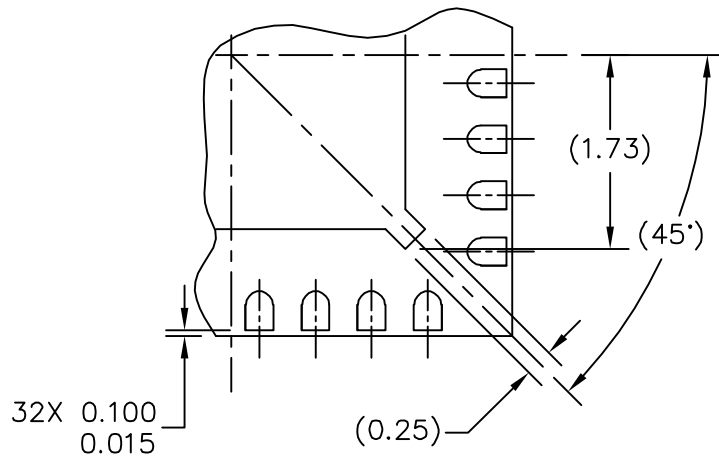


EXPOSED DIE ATTACH PAD

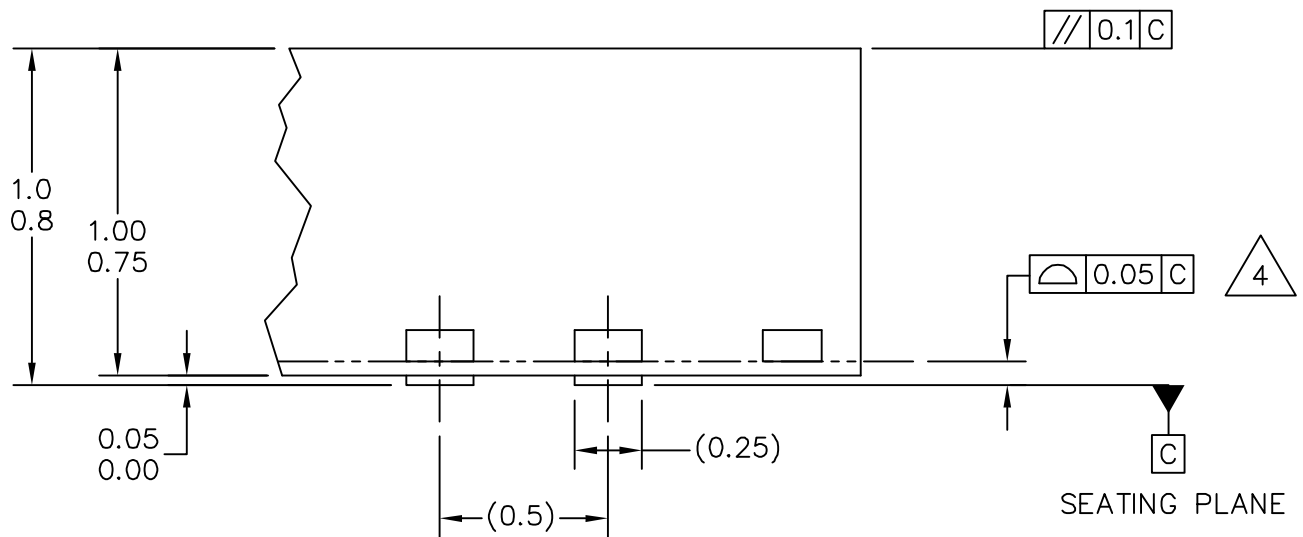


VIEW M-M

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) CASE OUTLINE	DOCUMENT NO: 98ARH99035A REV: K	
	STANDARD: JEDEC-MO-220 VHHD-2	
	SOT617-16 22 FEB 2016	

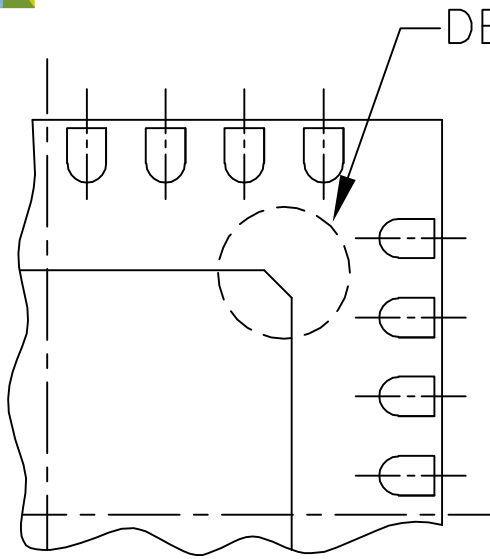


DETAIL N
CORNER CONFIGURATION

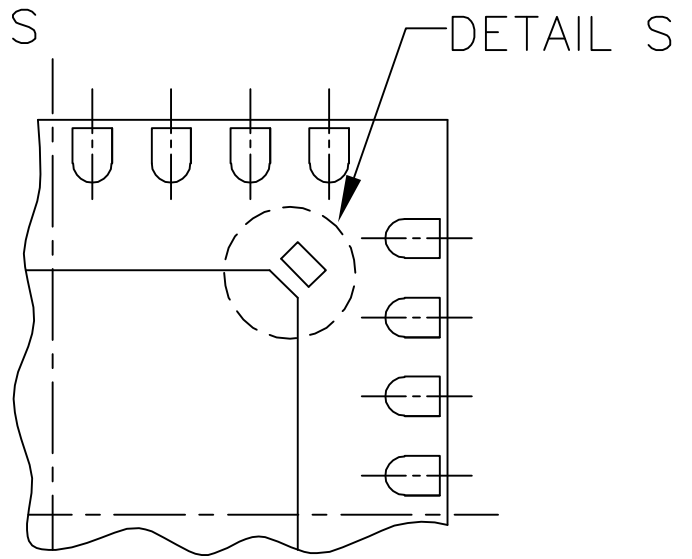


DETAIL G
VIEW ROTATED 90° CW

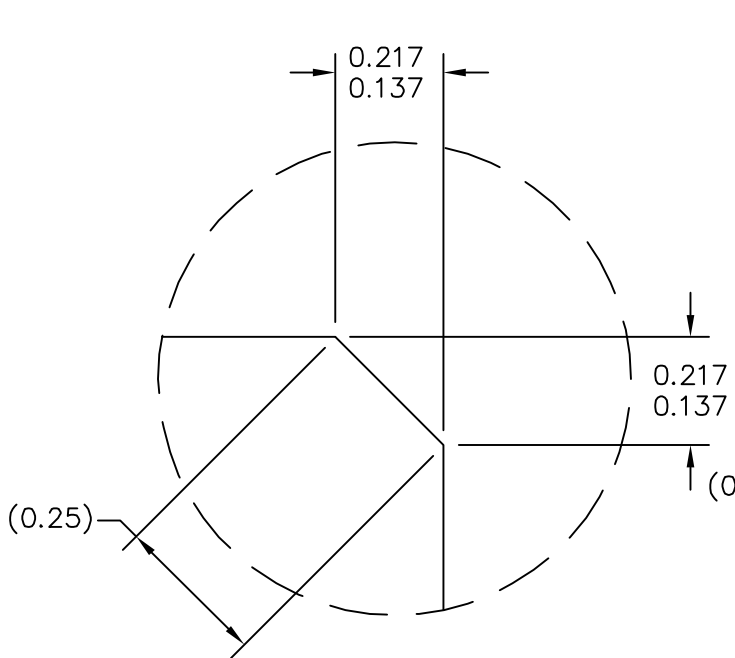
© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) CASE OUTLINE	DOCUMENT NO: 98ARH99035A	REV: K
	STANDARD: JEDEC-MO-220 VHHD-2	
	SOT617-16	22 FEB 2016



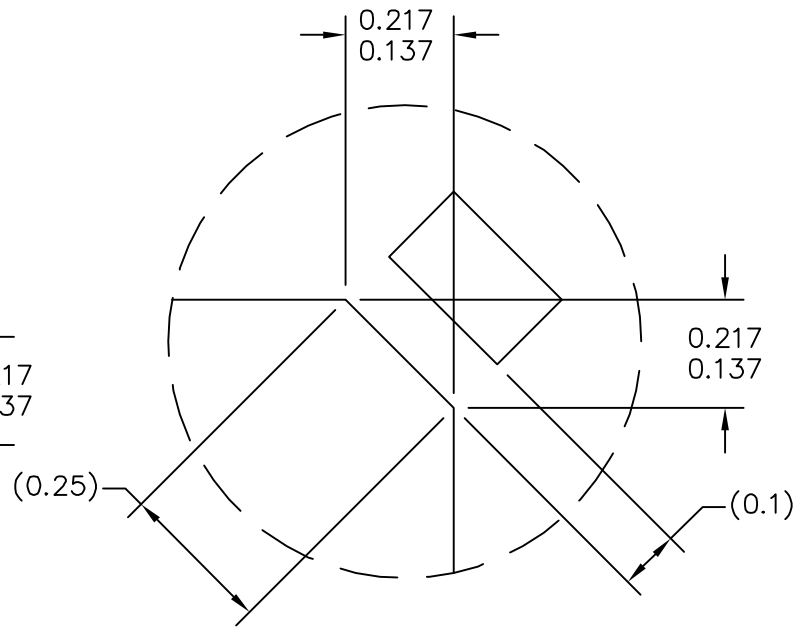
DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL M
BACKSIDE PIN 1 INDEX OPTION

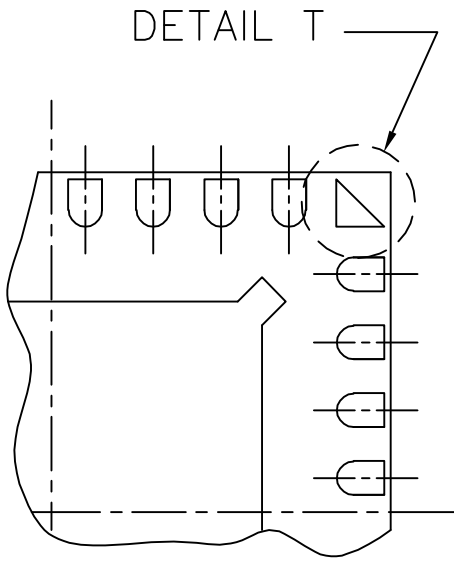


DETAIL S
PREFERRED BACKSIDE PIN 1 INDEX

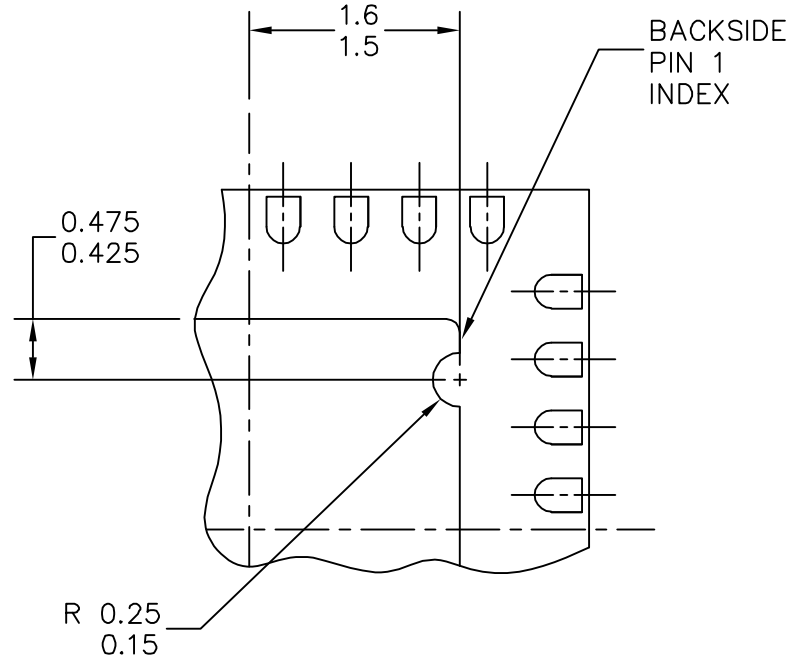


DETAIL S
BACKSIDE PIN 1 INDEX OPTION

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) CASE OUTLINE	DOCUMENT NO: 98ARH99035A	REV: K
	STANDARD: JEDEC-MO-220 VHHD-2	
	SOT617-16	22 FEB 2016

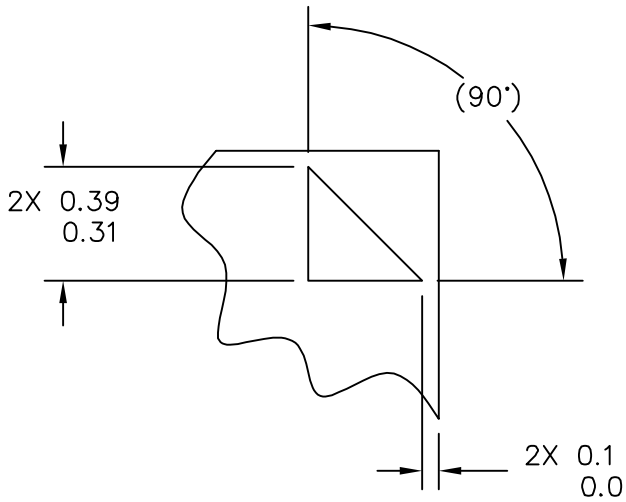


DETAIL T



DETAIL M
BACKSIDE PIN 1 INDEX OPTION

DETAIL M
BACKSIDE PIN 1 INDEX OPTION




DETAIL T
BACKSIDE PIN 1 INDEX OPTION

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) CASE OUTLINE		DOCUMENT NO: 98ARH99035A	REV: K
		STANDARD: JEDEC-MO-220 VHHD-2	
		SOT617-16	22 FEB 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) CASE OUTLINE	DOCUMENT NO: 98ARH99035A REV: K	
	STANDARD: JEDEC-MO-220 VHHD-2	
	SOT617-16 22 FEB 2016	